



Product Change Notification: MFOL-02TSEI860

Date:

12-Mar-2026

Product Category:

Memory

Notification Subject:

CCB 8135 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site.

Affected CPNs:

[MFOL-02TSEI860_Affected_CPN_03122026.pdf](#)

[MFOL-02TSEI860_Affected_CPN_03122026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-Free)	QMI519 (PFAS-Free)*	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Note: See reference PCN [CENO-16EGCZ399](#) for QMI519 Qual Report.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 03 June 2026 (date code: 2623)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	June 2026				
Work Week	10	11	12	13	14		23	24	25	26	27
Qual Report Availability		X									
Final PCN Issue Date		X									
Estimated Implementation Date							X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 12, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-02TSEI860_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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